Application No.: 09/661,281

AMENDMENTS TO THE ABSTRACT:

Please delete the Abstract of record and replace it with the following new Abstract as follows:

The present invention provides a circuit substrate which has a substrate including a first surface and a second surface opposite to the first surface. A first and a second conductor patterns are formed on the first and the second surface respectively. The second surface has larger surface roughness than the first surface. When the circuit substrate is mounted on another substrate, it is mounted to the other substrate via the second surface. The circuit substrate is capable of mounting a device or being mounted on another substrate to form an apparatus.